

**Dear Customer,**

Please find attached our INFINEON Technologies PCN:

### **Addition of Polyimide Passivation Layer to Automotive Gen6.2 IGBT Platform**

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before **19-October-2016**.
- Infineon aligns with the widely-recognized JEDEC STANDARD “**JESD46**“, which stipulates:  
“**Lack of acknowledgment of the PCN within 30 days constitutes acceptance of the change.**”

Your prompt reply will help Infineon Technologies to assure a smooth and well executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.

Infineon Technologies AG  
Postal Address Headquarters: Am Campeon 1-12, D-85579 Neubiberg, Phone +49 (0)89 234-0  
Chairman of the Supervisory Board: Wolfgang Mayrhuber  
Management Board: Dr. Reinhard Ploss (CEO), Dominik Asam, Dr. Helmut Gassel, Jochen Hanebeck  
Registered Office: Neubiberg Commercial Register  
Amtsgericht München HRB 126492

## Addition of Polyimide Passivation Layer to Automotive Gen6.2 IGBT Platform

### ► Products affected:

Sales Name	SP N°	OPN	Package
AUIRGPS4067D1	SP001512434	AUIRGPS4067D1	SUPER247COPAK

### ► Detailed Change Information:

**Subject:** Change to the IGBT Silicon process

**Reason:** Infineon strives to continuously improve the outgoing quality of all products for the benefit of our customers. Infineon facilities have invested significantly to modernize and improve wafer fabrication capability as part of our continuous improvement effort in order to meet today's quality demand.

**Description:** Addition of Polyimide Passivation Layer to Automotive Gen6.2 IGBT Platform

	Old	New
<b>Material</b>		
<b>Passivation</b>	Epoxy Passivation	Polyimide Passivation

### ► Product Identification:

Lot code information

### ► Impact of Change:

Polyimide passivation functions to protect the underlying silicon nitride passivation from thermo-mechanical damage. It also serves as additional protection layer for the termination structure from chemical contamination & electrical arcing which improves the robustness for customers handling and assembly issues. There are no changes to the SiN passivation layer.

### ► Attachments:

### ► Time Schedule:

■ Final qualification report:

Available

■ First samples available:

Upon Request

■ Intended start of delivery:

31-October-2016

If you have any questions, please do not hesitate to contact your local Sales office.